

HEATSINK FOR ELECTRICAL CIRCUITRY

ABSRTACT

A heatsink assembly comprising a substrate having an active circuitry, at least
5 one cavity located adjacent to at least one heat producing element of the active circuitry,
at least one vessel sealably coupled to said substrate in fluid communication with the at
least one cavity, and a phase change material (PCM) contained inside the vessel. The
vessel and at least one cavity configured to facilitate migration of the PCM from the
vessel into the at least one cavity for absorbing heat produced by the at least one heat
10 producing element of the active circuitry.

Figure 1